

# NRVHP820MFD

## Switch-Mode Power Rectifier

This ultrafast rectifier in the dual flag SO–8 flat lead package offers designers a unique degree of versatility and design freedom. The two devices are electrically independent and can be used separately, as common cathode, as common anode or in series as a function of board level layout. The exposed pad design provides low thermal resistance. The clip attach design creates a package with very efficient die size to board area ratio. While thermal performance is nearly the same as the DPAK package height and board footprint are less than half.

### Features

- New Package Provides Capability of Inspection and Probe After Board Mounting
- Low Forward Voltage Drop
- 175°C Operating Junction Temperature
- NRV Prefix for Automotive and Other Applications Requiring Unique Site and Control Change Requirements; AEC–Q101 Qualified and PPAP Capable
- These are Pb–Free and Halide–Free Devices

### Mechanical Characteristics:

- Case: Epoxy, Molded
- Epoxy Meets Flammability Rating UL 94–0 @ 0.125 in.
- Lead Finish: 100% Matte Sn (Tin)
- Lead and Mounting Surface Temperature for Soldering Purposes: 260°C Max. for 10 Seconds
- Device Meets MSL 1 Requirements

### Applications

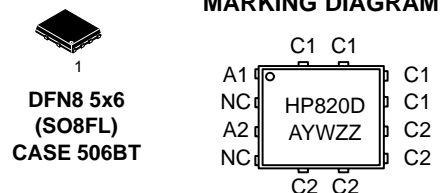
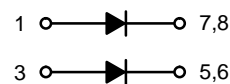
- Excellent Alternative to DPAK in Space–Constrained Automotive Applications
- Output Rectification in Switching Power Supplies
- Freewheeling Diode used with Inductive Loads



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## ULTRAFAST RECTIFIER 8 AMPERES (4x2), 200 VOLTS



DFN8 5x6  
(SO8FL)  
CASE 506BT

HP820D = Specific Device Code  
A = Assembly Location  
Y = Year  
W = Work Week  
ZZ = Lot Traceability

### ORDERING INFORMATION

| Device           | Package           | Shipping†             |
|------------------|-------------------|-----------------------|
| NRVHP820MFDT1G   | DFN8<br>(Pb–Free) | 1500 / Tape<br>& Reel |
| NRVHP820MFDT3G   | DFN8<br>(Pb–Free) | 5000 / Tape<br>& Reel |
| NRVHP820MFDWFT1G | DFN8<br>(Pb–Free) | 1500 / Tape<br>& Reel |
| NRVHP820MFDWFT3G | DFN8<br>(Pb–Free) | 5000 / Tape<br>& Reel |

†For information on tape and reel specifications, including part orientation and tape sizes, please refer to our Tape and Reel Packaging Specification Brochure, BRD8011/D.

# NRVHP820MFD

## MAXIMUM RATINGS (per diode unless noted)

| Rating  | Symbol                          | Value       | Unit             |
|---|---------------------------------|-------------|------------------|
| Peak Repetitive Reverse Voltage<br>Working Peak Reverse Voltage<br>DC Blocking Voltage                      | $V_{RRM}$<br>$V_{RWM}$<br>$V_R$ | 200         | V                |
| Average Rectified Forward Current<br>(Rated $V_R$ , $T_C = 170^\circ\text{C}$ )                             | $I_{F(AV)}$                     | 4.0         | A                |
| Peak Repetitive Forward Current,<br>(Rated $V_R$ , Square Wave, 20 kHz, $T_C = 169^\circ\text{C}$ )         | $I_{FRM}$                       | 8.0         | A                |
| Non-Repetitive Peak Surge Current<br>(Surge Applied at Rated Load Conditions Halfwave, Single Phase, 60 Hz) | $I_{FSM}$                       | 80          | A                |
| Storage Temperature Range   | $T_{stg}$                       | -65 to +175 | $^\circ\text{C}$ |
| Operating Junction Temperature  | $T_J$                           | -55 to +175 | $^\circ\text{C}$ |
| Unclamped Inductive Switching Energy (10 mH Inductor, Non-repetitive)                                       | $E_{AS}$                        | 20          | mJ               |
| ESD Rating (Human Body Model)   |                                 | 2           |                  |
| ESD Rating (Machine Model)  |                                 | M4          |                  |

Stresses exceeding those listed in the Maximum Ratings table may damage the device. If any of these limits are exceeded, device functionality should not be assumed, damage may occur and reliability may be affected.

## THERMAL CHARACTERISTICS (per diode unless noted)

| Characteristic  | Symbol          | Typ | Max | Unit               |
|---|-----------------|-----|-----|--------------------|
| Thermal Resistance, Junction-to-Case, Steady State<br>(Assumes 600 mm <sup>2</sup> 1 oz. copper bond pad, on a FR4 board) | $R_{\theta JC}$ | -   | 2.9 | $^\circ\text{C/W}$ |

## ELECTRICAL CHARACTERISTICS (per diode unless noted)

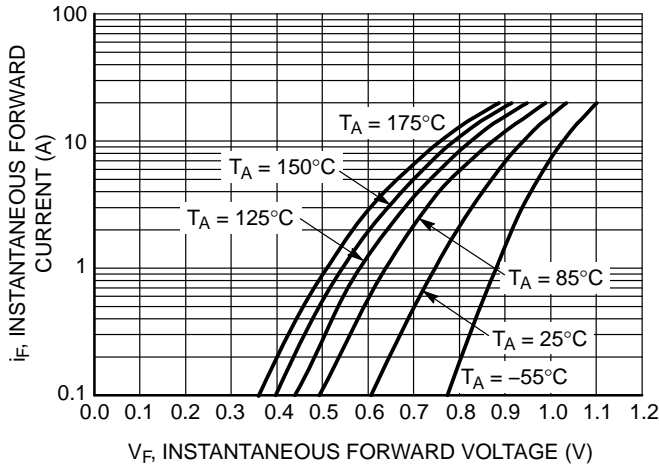
|  |          |                              |                              |               |
|--|----------|------------------------------|------------------------------|---------------|
| Instantaneous Forward Voltage (Note 1)<br>( $i_F = 4.0$ Amps, $T_J = 125^\circ\text{C}$ )<br>( $i_F = 4.0$ Amps, $T_J = 25^\circ\text{C}$ )<br>( $i_F = 8.0$ Amps, $T_J = 125^\circ\text{C}$ )<br>( $i_F = 8.0$ Amps, $T_J = 25^\circ\text{C}$ ) | $V_F$    | 0.71<br>0.85<br>0.72<br>0.92 | 0.80<br>0.95<br>0.90<br>1.05 | V             |
| Instantaneous Reverse Current (Note 1)<br>(Rated dc Voltage, $T_J = 125^\circ\text{C}$ )<br>(Rated dc Voltage, $T_J = 25^\circ\text{C}$ )  | $i_R$    | 2.00<br>0.02                 | 35<br>0.5                    | $\mu\text{A}$ |
| Reverse Recovery Time<br>$I_F = 3.0$ A, $V_R = 30$ V, $di/dt = 50$ A/ $\mu\text{s}$ , $T_J = 25^\circ\text{C}$   | $t_{rr}$ | 24                           | 30                           | ns            |
| Reverse Recovery Time<br>$I_F = 3.0$ A, $V_R = 30$ V, $di/dt = 50$ A/ $\mu\text{s}$ , $T_J = 50^\circ\text{C}$   | $t_{rr}$ | 27                           | 50                           | ns            |

Product parametric performance is indicated in the Electrical Characteristics for the listed test conditions, unless otherwise noted. Product performance may not be indicated by the Electrical Characteristics if operated under different conditions.

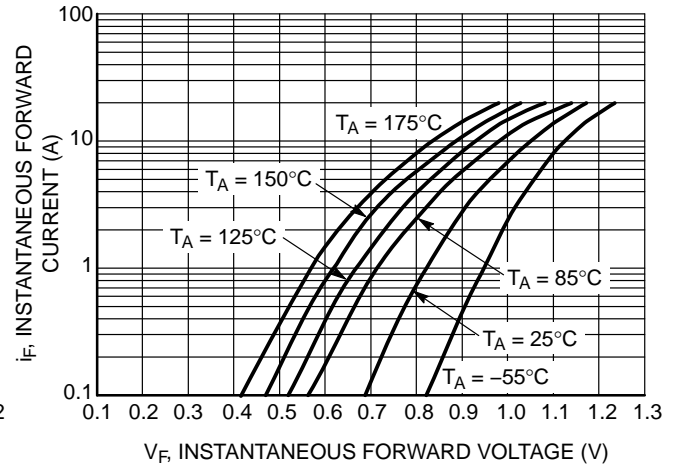
1. Pulse Test: Pulse Width = 300  $\mu\text{s}$ , Duty Cycle  $\leq 2.0\%$ .

# NRVHP820MFD

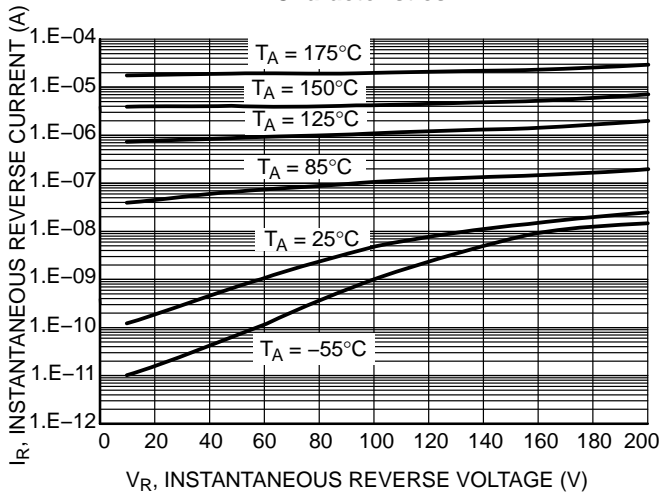
## TYPICAL CHARACTERISTICS



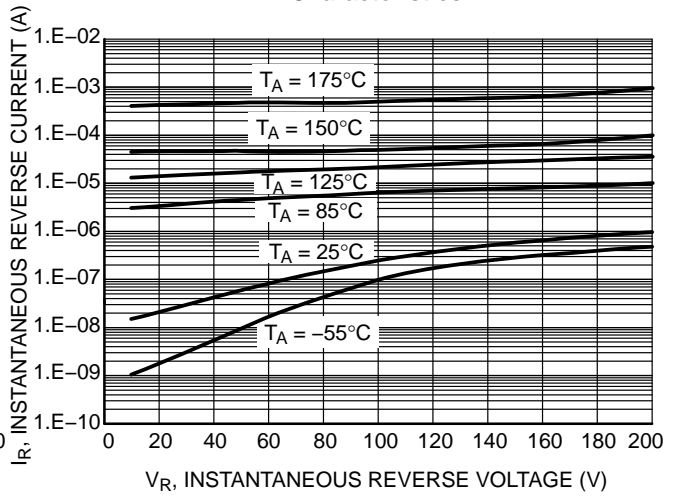
**Figure 1. Typical Instantaneous Forward Characteristics**



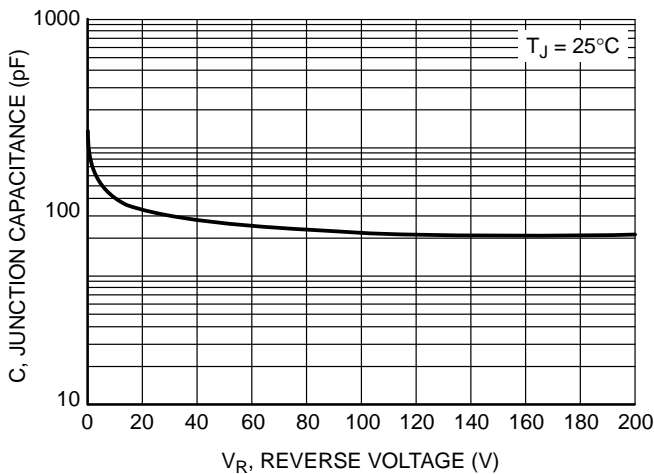
**Figure 2. Maximum Instantaneous Forward Characteristics**



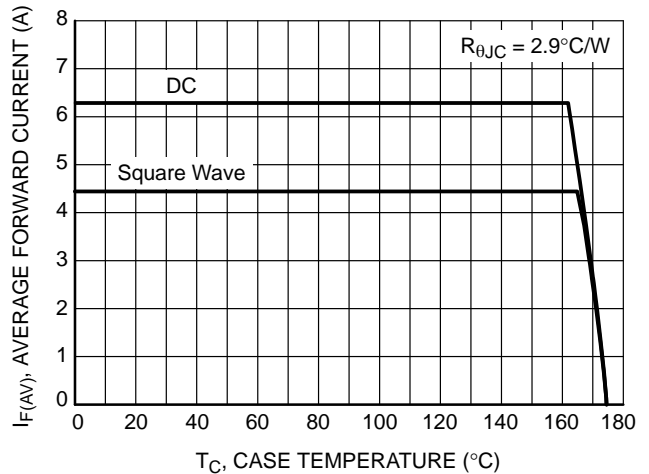
**Figure 3. Typical Reverse Characteristics**



**Figure 4. Maximum Reverse Characteristics**



**Figure 5. Typical Junction Capacitance**



**Figure 6. Current Derating per Device**

# NRVHP820MFD

## TYPICAL CHARACTERISTICS

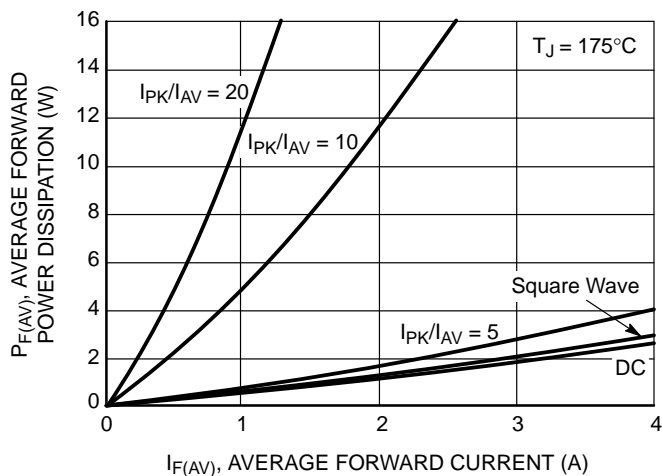


Figure 7. Forward Power Dissipation

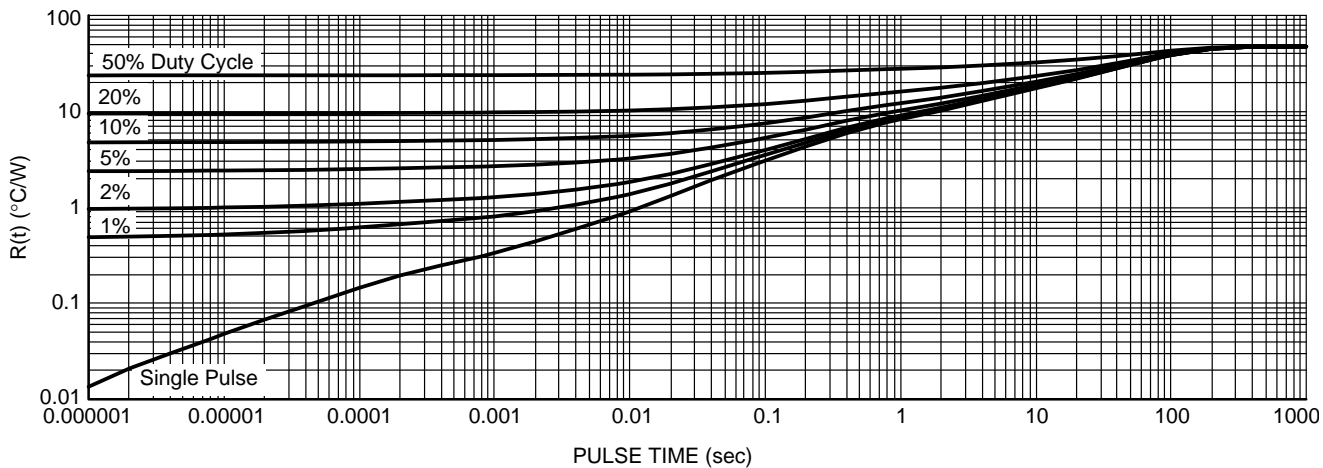
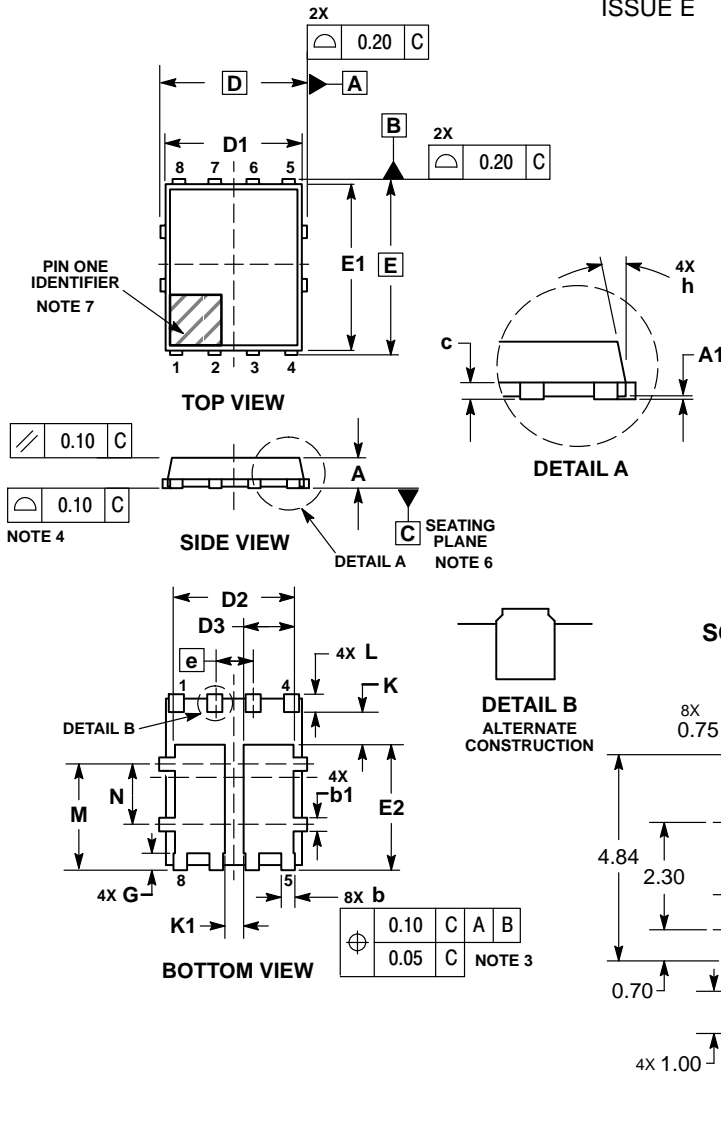


Figure 8. Typical Thermal Characteristics

# NRVHP820MFD

## PACKAGE DIMENSIONS

### DFN8 5x6, 1.27P Dual Flag (SO8FL-Dual) CASE 506BT ISSUE E



**NOTES:**

1. DIMENSIONING AND TOLERANCING PER ASME Y14.5M, 1994.
2. CONTROLLING DIMENSION: MILLIMETERS.
3. DIMENSION b APPLIES TO PLATED TERMINAL AND IS MEASURED BETWEEN 0.15 AND 0.30 MM FROM THE TERMINAL TIP.
4. PROFILE TOLERANCE APPLIES TO THE EXPOSED PAD AS WELL AS THE TERMINALS.
5. DIMENSIONS D1 AND E1 DO NOT INCLUDE MOLD FLASH, PROTRUSIONS, OR GATE BURRS.
6. SEATING PLANE IS DEFINED BY THE TERMINALS. A1 IS DEFINED AS THE DISTANCE FROM THE SEATING PLANE TO THE LOWEST POINT ON THE PACKAGE BODY.
7. A VISUAL INDICATOR FOR PIN 1 MUST BE LOCATED IN THIS AREA.

| DIM | MILLIMETERS |      |      |
|-----|-------------|------|------|
|     | MIN         | MAX  | MAX  |
| A   | 0.90        | ---  | 1.10 |
| A1  | ---         | ---  | 0.05 |
| b   | 0.33        | 0.42 | 0.51 |
| b1  | 0.33        | 0.42 | 0.51 |
| c   | 0.20        | ---  | 0.33 |
| D   | 5.15 BSC    |      |      |
| D1  | 4.70        | 4.90 | 5.10 |
| D2  | 3.90        | 4.10 | 4.30 |
| D3  | 1.50        | 1.70 | 1.90 |
| E   | 6.15 BSC    |      |      |
| E1  | 5.70        | 5.90 | 6.10 |
| E2  | 3.90        | 4.15 | 4.40 |
| e   | 1.27 BSC    |      |      |
| G   | 0.45        | 0.55 | 0.65 |
| h   | ---         | ---  | 12 ° |
| K   | 0.51        | ---  | ---  |
| K1  | 0.56        | ---  | ---  |
| L   | 0.48        | 0.61 | 0.71 |
| M   | 3.25        | 3.50 | 3.75 |
| N   | 1.80        | 2.00 | 2.20 |

DIMENSION: MILLIMETERS

\*For additional information on our Pb-Free strategy and soldering details, please download the ON Semiconductor Soldering and Mounting Techniques Reference Manual, SOLDERRM/D.

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